DB3X313J

Silicon epitaxial planar type

For small current rectification

■ Features

- Low forward voltage V_F and small reverse current I_R
- Low terminal capacitance C_t
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Basic Part Number

Dual DB2J313 (Common anode)

■ Packaging

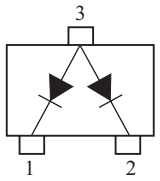
Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Package

- Code
  Mini3-G3-B
- Pin Name
  1: Cathode-1 3: Anode-1
  2: Cathode-2 Anode-2

■ Marking Symbol: 4K

■ Internal Connection



■ Absolute Maximum Ratings $T_a = 25°C$

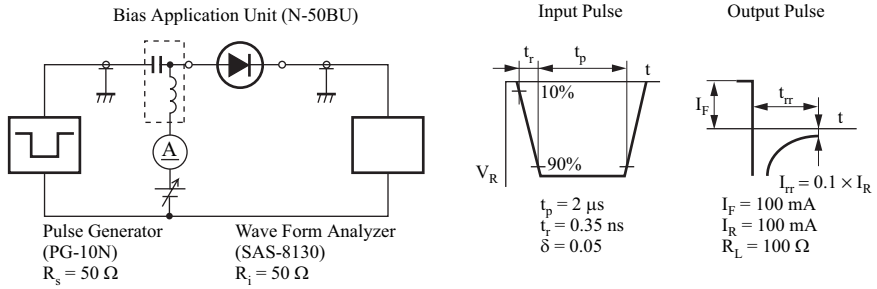
Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	30	V
Repetitive peak reverse voltage		V_{RRM}	30	V
Forward current (Average)	Single	$I_{F(AV)}$	200	mA
	Double *1		130	
Peak forward current	Single	I_{FM}	300	mA
	Double *1		220	
Non-repetitive peak reverse surge voltage *2	Single	I_{FSM}	1.0	A
	Double *1		0.7	
Junction temperature		T_j	125	°C
Storage temperature		T_{stg}	–55 to +125	°C

Note) ∗1: Value of each diode in double diodes used.
∗2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

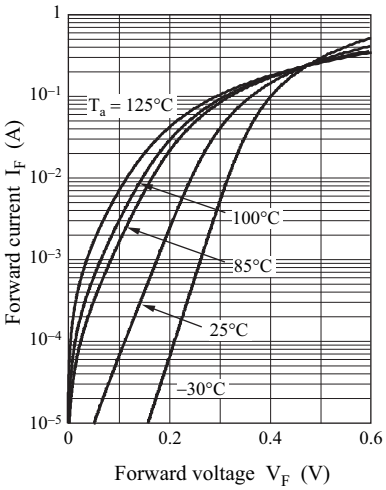
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 200 mA			0.55	V
Reverse current	I_R	V_R = 30 V			50	μA
Terminal capacitance	C_t	V_R = 10 V, f = 1 MHz		3.8		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ =100 mA, $I_{rr} = 0.1 \times I_R$, R_L = 100 Ω		1.5		ns

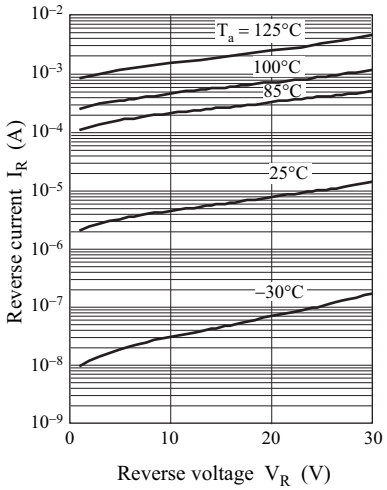
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 1 GHz
∗: t_{rr} measurement circuit



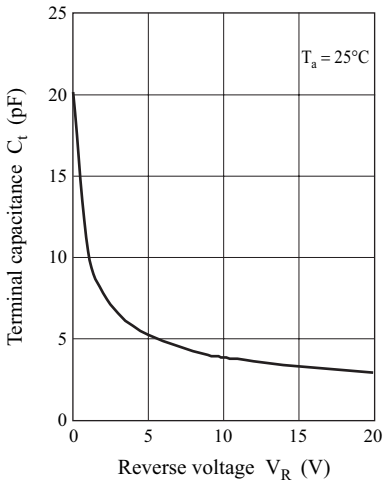
I_F — V_F



I_R — V_R

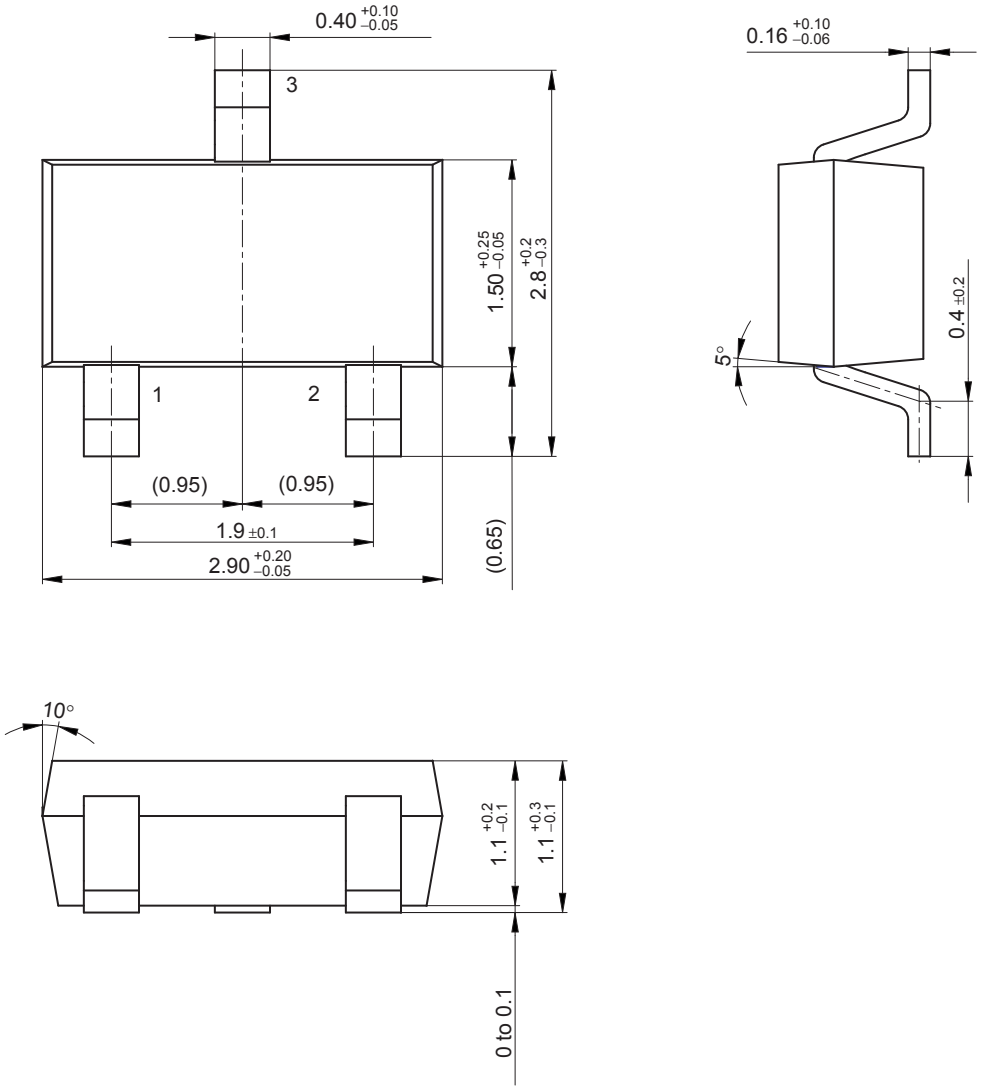


C_t — V_R



Mini3-G3-B

Unit: mm



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